

SESSION IV

High Volume Manufacturing – Special Session

Chair: Jim Oakes, Raytheon Company

With the increasing production volumes of GaAs devices and circuits required for high-speed applications in both analog and digital products, many wafer fab operations are processing over 10,000 wafers per year and the industry is looking to 150-mm wafers to increase capacity and lower costs. Then the millions of devices produced must all be packaged and tested. How does a fab operation move from low or moderate production volumes to a high-volume operation? How have companies moved from 3-inch to 100-mm wafers and will this help in moving to 150-mm? What changes are needed in equipment and approach? A panel representing a cross section of GaAs manufacturing in the US, Japan and Europe has been assembled to speak to these issues. The panel members are:

Mr. Sheo Khetan, VP of Manufacturing, Anadigics

Mr. Seigo Sano, Senior Engineer, Fujitsu

Mr. Alan Lightfoot, Operations Manager, Motorola

Dr. Art Geissberger, VP of Wafer Fabrication, RFMD

Dr. E. Pettenpaul, General Manager, Siemens

Mr. Ian Burrows, VP of Fab Operations, Vitesse

Each panelist will present his observations and the audience will be able to ask questions. Come and benchmark your operation against some of the leaders.